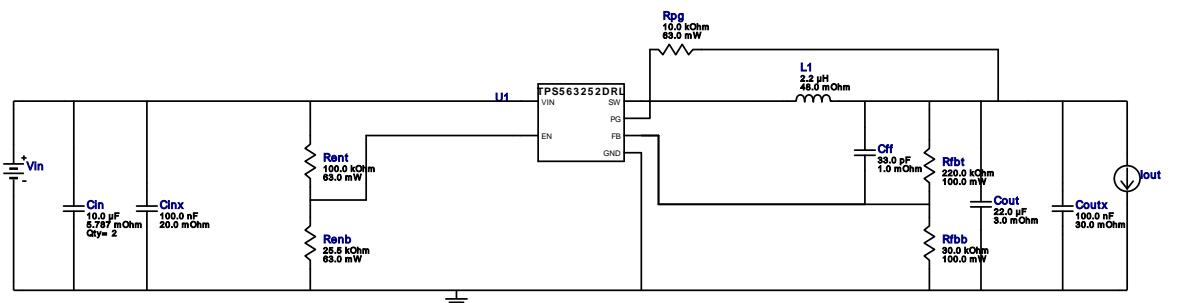


WEBENCH® Design Report

Design : 20 TPS563252DRLR
 TPS563252DRLR 6V-8.4V to 5.00V @ 3A

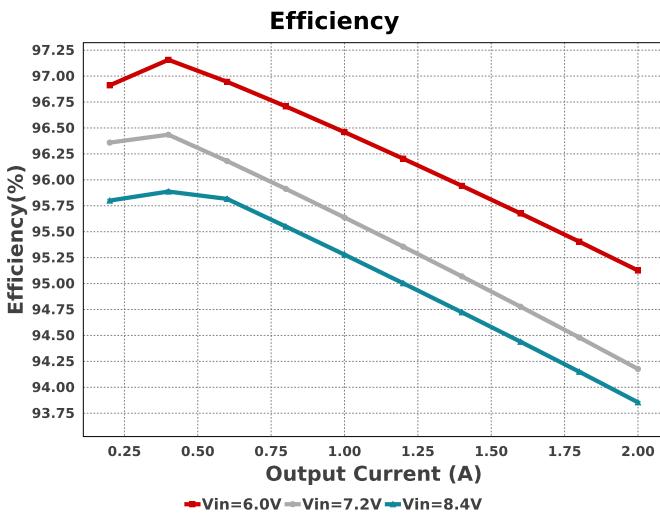
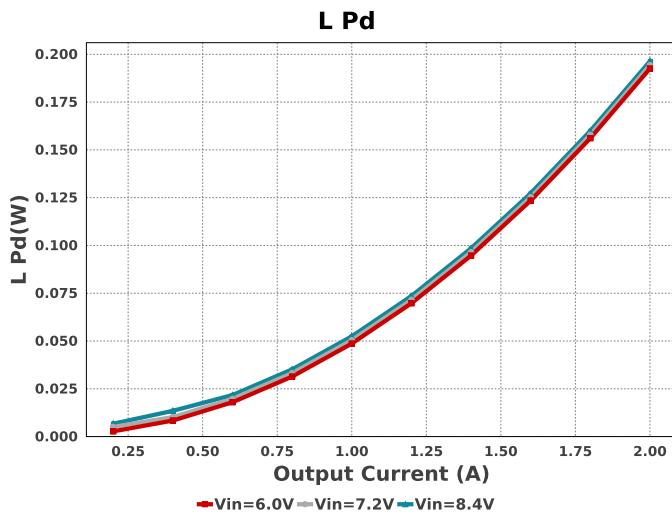
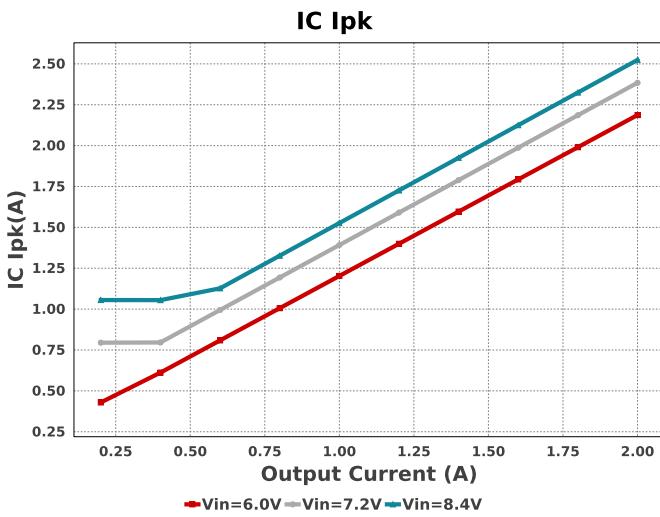
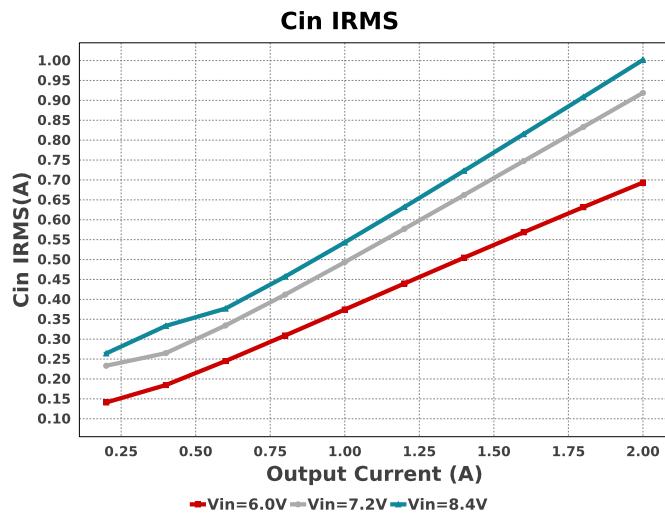
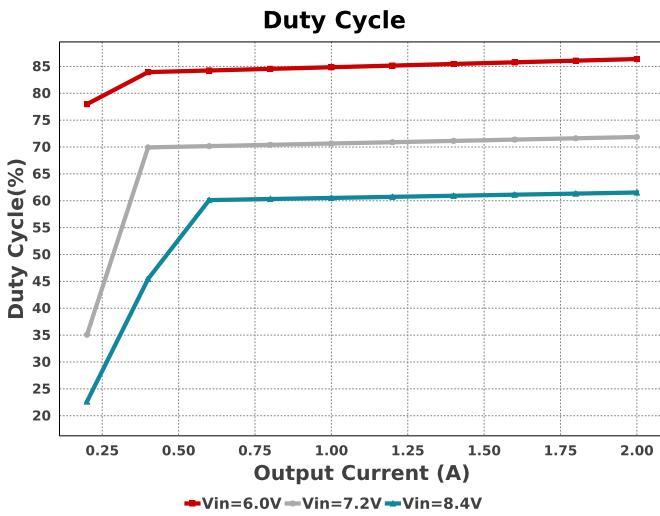
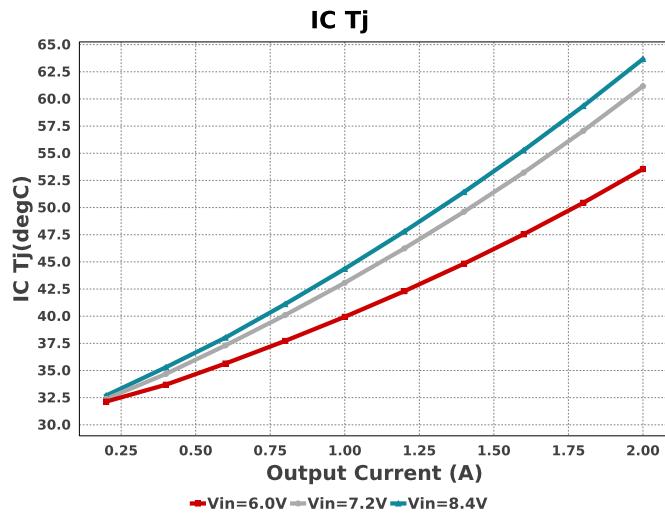
VinMin = 6.0V
 VinMax = 8.4V
 Vout = 5.0V
 Iout = 2.0A
 Device = TPS563252DRLR
 Topology = Buck
 Created = 2025-08-19 18:19:34.185
 BOM Cost = \$0.66
 BOM Count = 13
 Total Pd = 0.65W

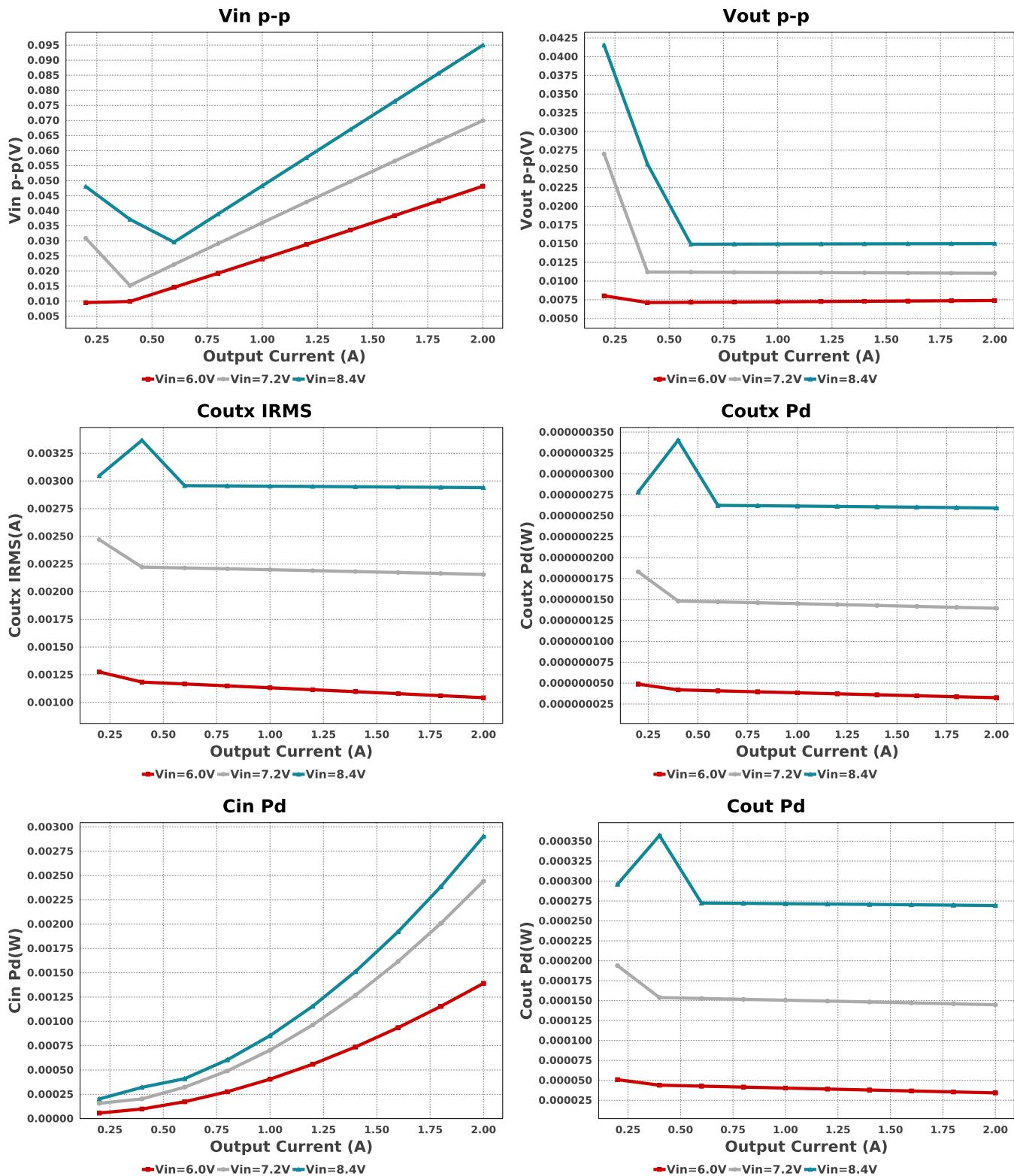


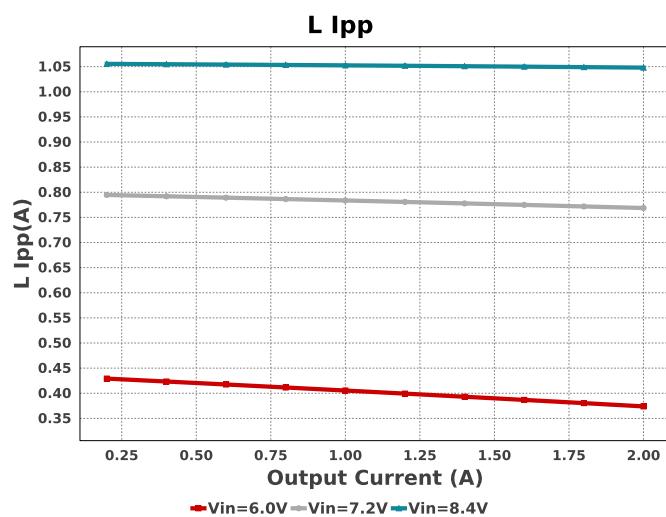
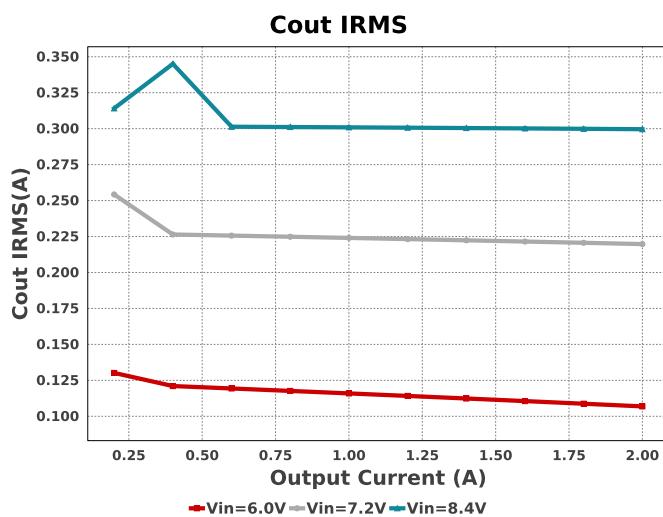
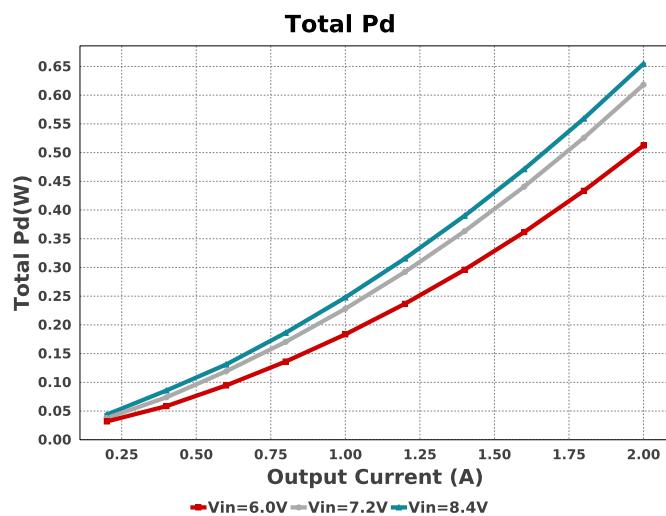
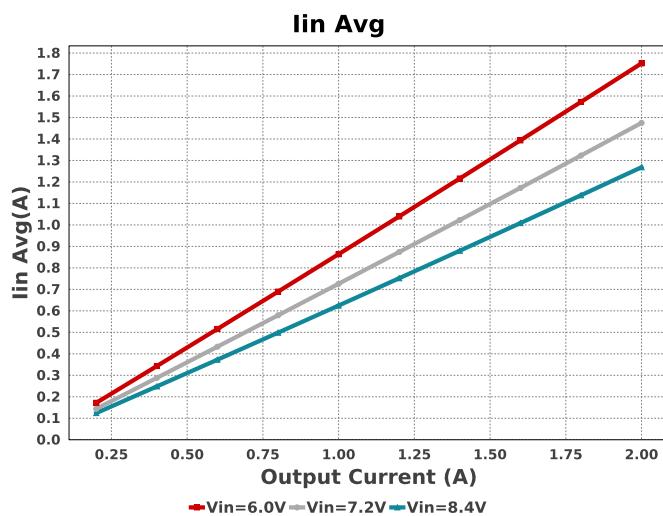
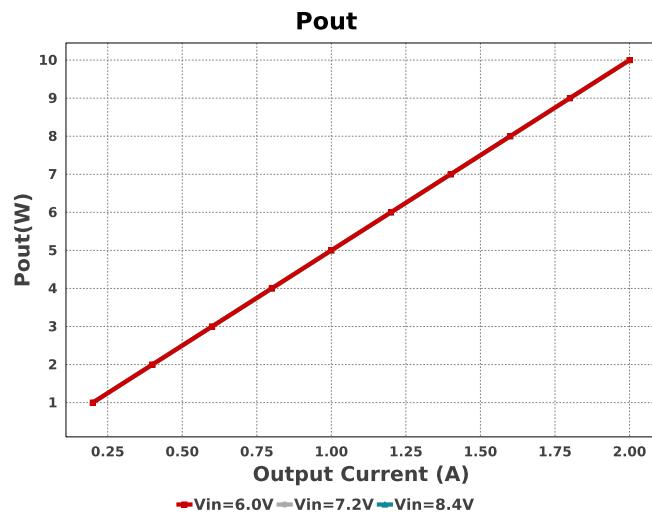
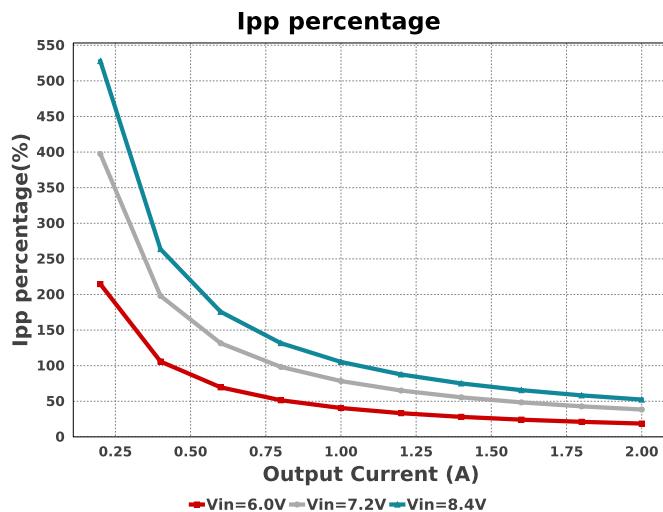
Electrical BOM

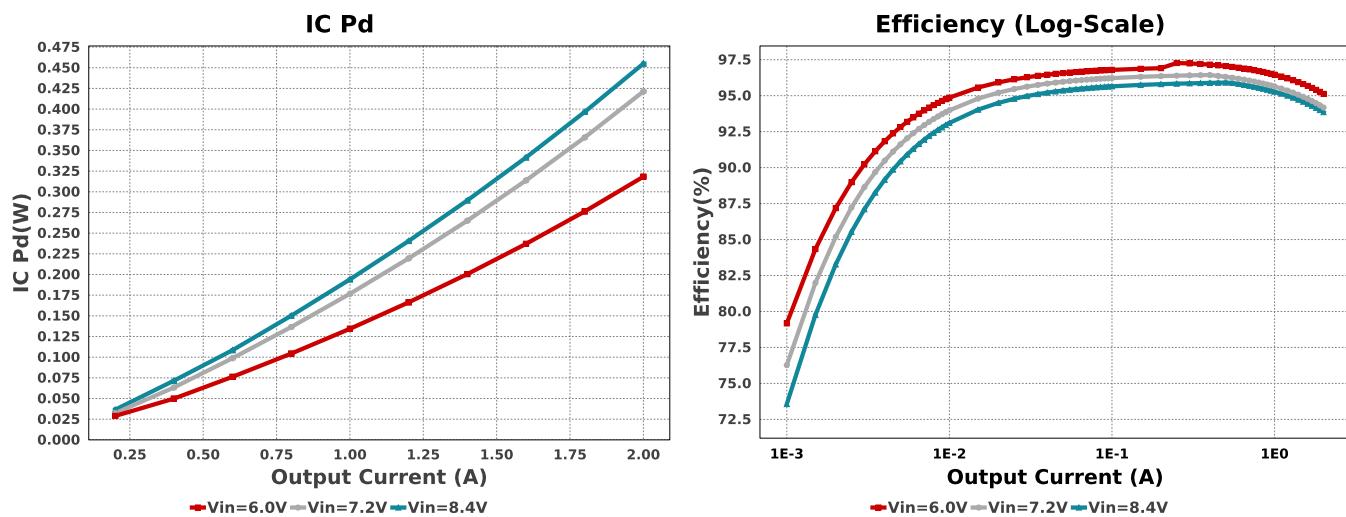
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cff	MuRata	GRM1555C1E330JA01D Series= C0G/NPO	Cap= 33.0 pF ESR= 1.0 mOhm VDC= 25.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm²
Cin	Taiyo Yuden	MSASE21GAB5106KTNA01 Series= X5R	Cap= 10.0 uF ESR= 5.787 mOhm VDC= 16.0 V IRMS= 2.755 A	2	\$0.03	0805 7 mm²
Cinx	MuRata	GRM188R71H104KA93D Series= X7R	Cap= 100.0 nF ESR= 20.0 mOhm VDC= 50.0 V IRMS= 3.8 A	1	\$0.02	0603 5 mm²
Cout	MuRata	GRM21BR61A226ME44L Series= X5R	Cap= 22.0 uF ESR= 3.0 mOhm VDC= 10.0 V IRMS= 3.84 A	1	\$0.09	0805 7 mm²
Coutx	MuRata	GRM188R71E104KA01D Series= X7R	Cap= 100.0 nF ESR= 30.0 mOhm VDC= 25.0 V IRMS= 1.51 A	1	\$0.01	0603 5 mm²
L1	Pulse Engineering	PA4332.222NLT	L= 2.2 μH 48.0 mOhm	1	\$0.26	PA4332 27 mm²
Renb	Vishay-Dale	CRCW040225K5FKED Series= CRCW..e3	Res= 25.5 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm²
Rent	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm²
Rfbb	Yageo	RC0603FR-0730KL Series= ?	Res= 30.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm²
Rfbt	Yageo	RC0603FR-07220KL Series= ?	Res= 220.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm²
Rpg	Vishay-Dale	CRCW040210K0FKED Series= CRCW..e3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
U1	Texas Instruments	TPS563252DRLR	Switcher	1	\$0.15	DRL0006A 7 mm ²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	1.002 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	2.903 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	299.615 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	269.31 μ W	Capacitor	Output capacitor power dissipation
5.	Coutx IRMS	2.94 mA	Capacitor	Output capacitor_x RMS ripple current
6.	Coutx Pd	259.28 nW	Capacitor	Output capacitor_x power loss
7.	IC Ipk	2.524 A	IC	Peak switch current in IC
8.	IC Pd	455.03 mW	IC	IC power dissipation
9.	IC Tj	63.672 degC	IC	IC junction temperature
10.	IC Tolerance	9.0 mV	IC	IC Feedback Tolerance
11.	ICThetaJA Effective	74.0 degC/W	IC	IC junction-to-ambient thermal resistance with TI EVM
12.	Iin Avg	1.268 A	IC	Average input current
13.	Ipp percentage	52.404 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
14.	L Ipp	1.048 A	Inductor	Peak-to-peak inductor ripple current
15.	L Pd	196.39 mW	Inductor	Inductor power dissipation
16.	Cin Pd	2.903 mW	Power	Input capacitor power dissipation
17.	Cout Pd	269.31 μ W	Power	Output capacitor power dissipation
18.	Coutx Pd	259.28 nW	Power	Output capacitor_x power loss
19.	IC Pd	455.03 mW	Power	IC power dissipation
20.	L Pd	196.39 mW	Power	Inductor power dissipation
21.	Total Pd	654.723 mW	Power	Total Power Dissipation
22.	BOM Count	13	System	Total Design BOM count
23.	Duty Cycle	61.534 %	Information	Duty cycle
24.	Efficiency	93.855 %	Information	Steady state efficiency
25.	FootPrint	85.0 mm ²	Information	Total Foot Print Area of BOM components
26.	Frequency	856.786 kHz	Information	Switching frequency
27.	Iout	2.0 A	System	Iout operating point
28.	Mode	CCM	Information	Conduction Mode
29.	Pout	10.0 W	System	Total output power
30.	Total BOM	\$0.66	Information	Total BOM Cost
31.	Vin	8.4 V	System	Vin operating point
32.	Vin p-p	95.0 mV	Information	Peak-to-peak input voltage
33.	Vout	5.0 V	System	Operational Output Voltage
34.	Vout Actual	5.0 V	Information	Vout Actual calculated based on selected voltage divider resistors
35.	Vout Tolerance	3.304 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
36.	Vout p-p	15.009 mV	Information	Peak-to-peak output ripple voltage

Design Inputs

Name	Value	Description
Iout	2.0	Maximum Output Current
VinMax	8.4	Maximum input voltage
VinMin	6.0	Minimum input voltage
Vout	5.0	Output Voltage
base_pn	TPS563252	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of L_1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

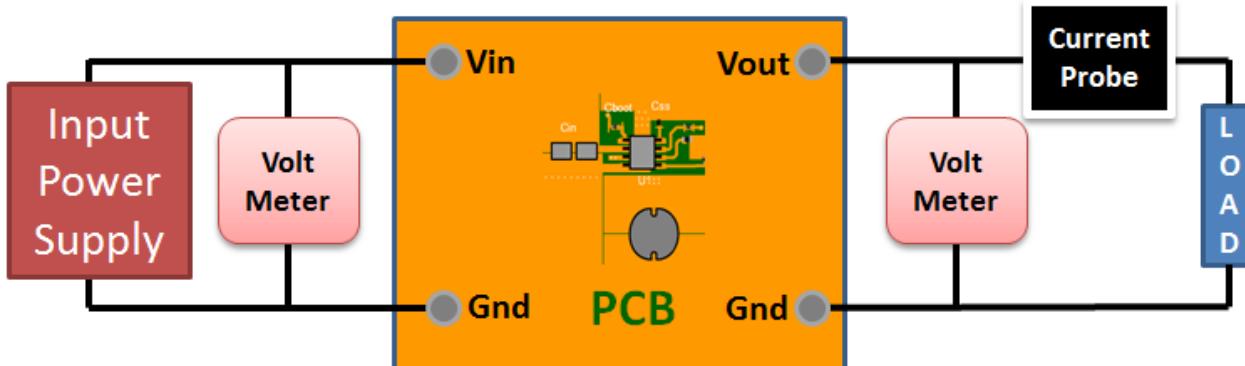
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 6.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum I_{out} of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : 49E76D69039D26F6[v1]
2. **TPS563252 Product Folder** : <https://www.ti.com/product/TPS563252> : contains the data sheet and other resources.

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